



30V N-CHANNEL ENHANCEMENT MODE MOSFET **PowerDI**

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
	$3.8 \text{m}\Omega$ @ $V_{GS} = 10V$	140A
30V	$6m\Omega$ @ $V_{GS} = 4.5V$	110A

Features and Benefits

- Low R_{DS(ON)} Minimizes On-State Losses
- Excellent Q_{gd} x R_{DS(ON)} Product (FOM)
- Advanced Technology for DC-DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher **Density End Products**
- 100% Unclamped Inductive Switching Ensures More Reliability
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Backlighting
- **Power Management Functions**
- DC-DC Converters

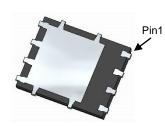
Mechanical Data

- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)

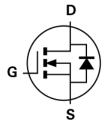




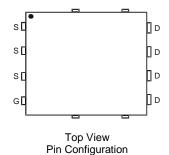
Notes:



Bottom View



Internal Schematic



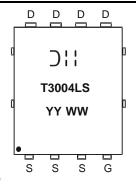
Ordering Information (Note 4)

Part Number	Case	Packaging
DMT3004LPS-13	PowerDI [®] 5060-8	2,500/Tape & Reel

PowerDI[®]5060-8

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + CI) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



⊃¦¦ = Manufacturer's Marking T3004LS = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 15 = 2015)WW = Week (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage		V_{DSS}	30	V
Gate-Source Voltage		V_{GSS}	+20 -16	V
Continuous Drain Current, V _{GS} = 10V (Note 5)	$T_A = +25$ °C $T_A = +70$ °C	I _D	21 17	А
Continuous Drain Current, V _{GS} = 10V	$T_C = +25$ °C $T_C = +70$ °C	I _D	140 110	А
Maximum Continuous Body Diode Forward Current (Note 5) T _A = +25°C		Is	3	Α
Maximum Continuous Body Diode Forward Current $T_C = +25^{\circ}C$		I _S	48	Α
Maximum Body Diode Forward Pulse Current $T_C = +25$ °C		I _{SM}	180	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)		I _{DM}	180	Α
Avalanche Current, L=0.3mH		I _{AS}	27	A
Avalanche Energy, L=0.3mH	E _{AS}	110	mJ	

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Power Dissipation	T _A = +25°C (Note 5)	P _D	2.7	W	
	$T_C = +25^{\circ}C$		113		
Thermal Resistance, Junction to Ambient (Note 5) Steady State		$R_{\theta JA}$	47	°C/W	
Thermal Resistance, Junction to Case		R ₀ JC	1.1	C/VV	
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Electrical Characteristics (T_A = +25°C, unless otherwise specified.)

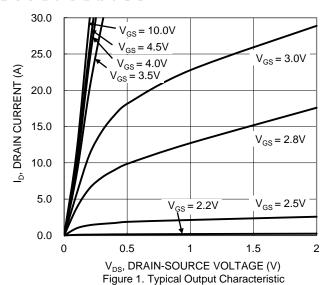
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 24V$, $V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		ı	±100	nA	$V_{GS} = +20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage	$V_{GS(TH)}$	1	_	3	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		_	_	3.8	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R _{DS(ON)}		1	6		$V_{GS} = 4.5V, I_D = 7A$	
Diode Forward Voltage	V_{SD}	_	0.70	1	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	_	2,370	_		$V_{DS} = 15V$, $V_{GS} = 0V$, $f = 1MHz$	
Output Capacitance	Coss		1,360		pF		
Reverse Transfer Capacitance	C _{rss}	_	240	_			
Gate Resistance	R_g	_	0.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_g	_	43.7	_		V _{DS} = 15V, I _D = 20A	
Gate-Source Charge	Q_{gs}	_	6.9	_	nC		
Gate-Drain Charge	Q_{gd}	_	8	_			
Turn-On Delay Time	t _{D(ON)}	_	6.2	_		$V_{DD} = 15V, V_{GS} = 10V,$ $R_{G} = 3\Omega, R_{L} = 0.75\Omega$	
Turn-On Rise Time	t _R	_	4.2	_	20		
Turn-Off Delay Time	t _{D(OFF)}	_	21	_	ns		
Turn-Off Fall Time	t _F	_	8	_			
Body Diode Reverse Recovery Time	t _{RR}	_	25	_	ns	1 45A 31/31 500A/s	
Body Diode Reverse Recovery Charge	Q _{RR}	_	37	_	nC	I _F = 15A, di/dt = 500A/μs	

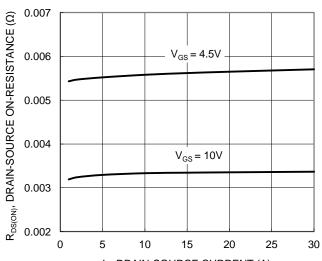
Notes: 5. R_{BJA} is determined with the device mounted on FR-4 substrate PC board, 2oz copper, with 1in. square copper plate. R_{BJC} is guaranteed by design while R_{BJA} is determined by the user's board design.

^{6.} Short duration pulse test used to minimize self-heating effect.

^{7.} Guaranteed by design. Not subject to product testing.







I_D, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

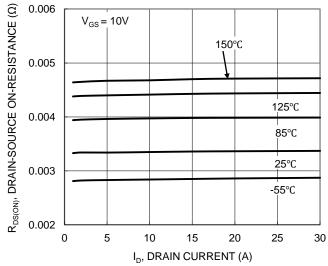


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

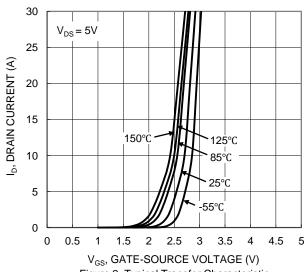
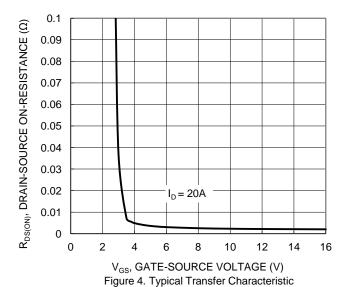


Figure 2. Typical Transfer Characteristic



2.5 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 2 $V_{GS} = 10V, I_{D} = 20A$ 1.5 $V_{GS} = 4.5V, I_{D} = 15A$ 1 0.5 0 25 50 -50 -25 0 75 100 125 150

T_J, JUNCTION TEMPERATURE (°C) Figure 6. On-Resistance Variation with Junction Temperature





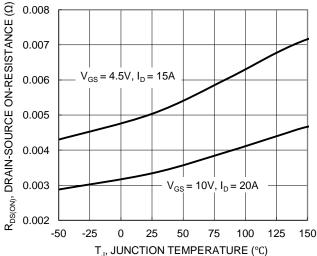
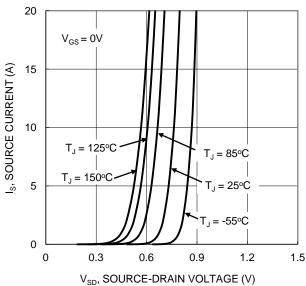
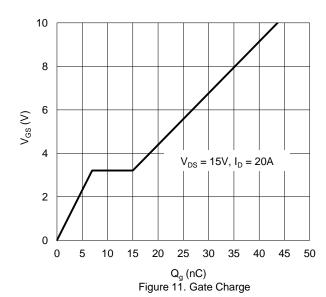


Figure 9. On-Resistance Variation with Junction Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V)
Figure 9. Diode Forward Voltage vs. Current



25

2.5

-50

-25

T_J, JUNCTION TEMPERATURE (°C) Figure 8. Gate Threshold Variation vs. Junction Temperature

50

75

100

125

150

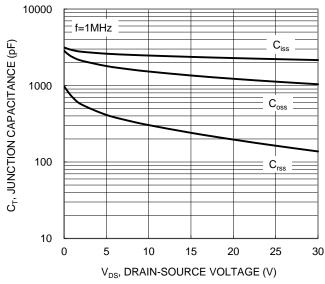
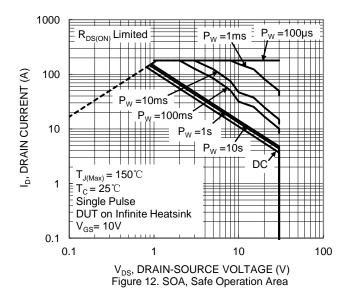


Figure 10. Typical Junction Capacitance





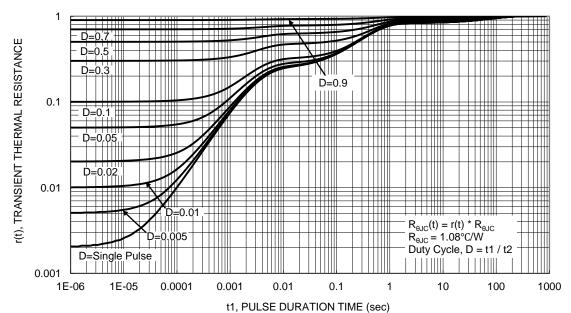


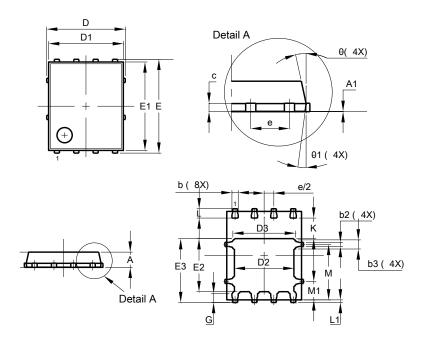
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.

POWERDI®5060-8

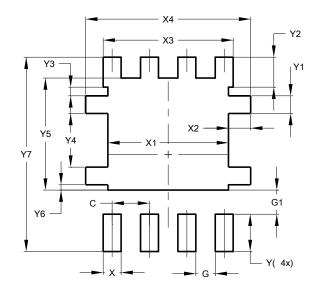


POWERDI®5060-8					
Dim	Min	Max	Тур		
Α	0.90	1.10	1.00		
A1	0.00	0.05	-		
b	0.33	0.51	0.41		
b2	0.200	0.350	0.273		
b3	0.40	0.80	0.60		
c D	0.230	0.330	0.277		
	5	.15 BS	\circ		
D1	4.70	5.10	4.90		
D2	3.70	4.10	3.90		
D3	3.90	4.30	4.10		
Е	6	3.15 BS	\circ		
E1	5.60	6.00	5.80		
E2	3.28	3.68	3.48		
E3	3.99	4.39	4.19		
е	1.27 BSC				
G	0.51	0.71	0.61		
K	0.51	_	_		
L	0.51	0.71	0.61		
L1	0.100	0.200	0.175		
М	3.235	4.035	3.635		
М1	1.00	1.40	1.21		
Θ	10°	12°	11°		
Θ1	6°	8°	7°		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/_files/datasheets/ap02001.pdf for the latest version.

POWERDI®5060-8



Dimensions	Value (in mm)				
C	1.270				
G	0.660				
G1	0.820				
Х	0.610				
X1	4.100				
X2	0.755				
Х3	4.420				
X4	5.610				
Υ	1.270				
Y1	0.600				
Y2	1.020				
Y3	0.295				
Y4	1.825				
Y5	3.810				
Y6	0.180				
Y7	6.610				

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